

LS4 WAFFLE PACK LID (GP-LS4-LID-T)

TECHNICAL DATASHEET

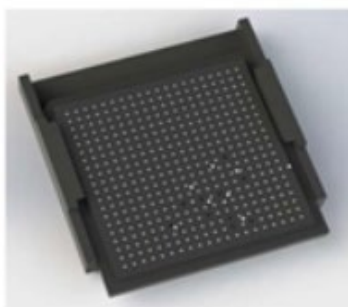
Shipping today's thin die (<250µm) in industry standard 4" waffle packs presents a challenge for many semiconductor manufacturers. Thin devices packaged in these 4" chip trays have a tendency to migrate out of pocket causing increased cost in rework labor and yield loss.

Gel-Pak's LS4 padded waffle pack lid prevents thin die from migrating out of 4" waffle pack/chip tray pockets during shipping and handling. The LS4 lid, based on same technology as the patented LCS2 lid, is designed to work with Gel-Pak's standard 4" clip which tightly compresses the tray and lid to prevent die migration.



LS4 FEATURES AND BENEFITS

- Uniformly seals each individual tray pocket
- Helps compensate for common waffle pack lid/tray warpage conditions that create gaps that enable die migration
- Saves significant costs associated with yield loss, rework labor and RMAs caused by die migration issues.
- Integrated anti-static Tyvek interleaf material eliminates the manual placement and misalignment and/or pinching of Tyvek paper when loading waffle pack
- Static dissipative padded lid (SR < E9 ohms)
- Silicone-free



Die Migration

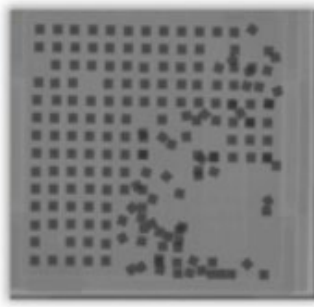


Image of Die Migration under X-Ray



4" Padded Waffle Pack Lid Diagram

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